

METHOD AND SYSTEM OF WIRE BONDING FOR USE IN FABRICATION OF SEMICONDUCTOR PACKAGE

ABSTRACT

10075043 001200
200120 0405 2001

A method and a system of wire bonding for use in semiconductor package fabrication are proposed. When one wire-bonded substrate unit of a substrate mounted with chips is introduced into a testing region, a next adjacent substrate unit is simultaneously formed with bonding wires in a wire-bonding region. In the testing region, the wire-bonded substrate unit is tested for wire bonding quality. If no wire opening or short ^{drawn} occurs, the wire-bonded substrate unit is readily used for subsequent package fabrication. If wire opening or short is detected, a controlling module associated with the testing region generates a control signal to the wire-bonding region for interrupting a wire-bonding process, whereby causes of wire opening or short are overcome, and defective bonding wires are reworked. Therefore, inferior or malfunction is timely detected, making overall fabrication process more time-effectively implemented; and inferior are reworked for later usage, thereby significantly reducing fabrication costs.

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